

Technical Note

General-purpose Operational Amplifiers / Comparators

NOW SERIES Comparators

LM393MX,LM2903MX,LM339MX,LM2901MX

No.11094ECT06

Description

The Universal Standard family LM393 / LM339 / LM2903 / LM2901 monolithic ICs integrate two / four independent comparators on a single chip and feature high gain, low power consumption, and an operating voltage range from 2[V] to 36[V] (single power supply).



Features

- Operating temperature range Commercial Grade LM339/393 family: 0[°C] to +70[°C] Extended Industrial Grade LM2903/2901 family: -40[°C] to +85[°C]
- 2) Open collector output
- 3) Single / dual power supply compatible
- 4) Low supply current
- 0.8[mA] typ.(LM2901/339 family) 0.4[mA] typ.(LM2903/393 family)
- 5) Low input-bias current: 25[nA] typ.
- a) Low input-bias current: 25[nA] typ.b) Low input-offset current: 5[nA] typ.
- 7) Input common-mode voltage range, including ground
- B) Differential input voltage range equal to maximum rated supply voltage
- 9) Low output saturation voltage
- 10) TTL,MOS,CMOS compatible output

Pin Assignment







LM2901MX

●Absolute Maximum Ratings (Ta=25°C)

Parameter	Sympol	Rating							
Parameter	Symbol	LM393 family	LM339 family	LM2903 family	LM2901 family	Unit			
Supply Voltage	V⁺-GND		+36						
Input Differential Voltage	Vid		±36						
Common-mode Input Voltage	Vicm	-0.3 to +36							
Operating Temperature Range	Topr	0 to	+70	-40 to +85					
Storage Temperature Range	Tstg	-65 to +150							
Maximum Junction Temperature	Tjmax	+150							

Electric Characteristics

OLM393/339 Family(Unless otherwise specified, V⁺=+5[V])

					Lin	nits					
Parameter	Symbol	Temperature range	L	M393 fam	ily	L	M339 fam	ily	Unit	Condition	Fig.No
		- J.	Min.	Тур.	Max.	Min.	Тур.	Max.			
Input Offset Voltage (*1)	VIO	25°C	_	1	7	-	2	7	mV	V ⁺ =5 to 30[V],VO=1.4[V], RS=0[Ω]	88
input Onset voltage (1)	VIO	Full range	-	-	9	_	_	15	mv	VCM=0[V] to V ⁺ -1.5[V]	00
Input Bias Voltage (*1)	IIB	25°C	-	25	250	_	25	250	nA	IIN(+) or IIN(-)	88
Input bias voltage (1)	ПD	Full range	I	-	400	_	—	400	ΠA	VCM=0[V]	00
Input Offset Current (*1)	IIO	25°C	-	5	50	_	5	50	nA	IIN(+)-IIN(-),VCM=0[V]	88
	110	Full range	-	_	150	_	_	150			00
Input Common-mode	VICR	25°C	0	-	V ⁺ -1.5	—	_	V ⁺ -1.5	v	V ⁺ =30[V]	88
Voltage Range	VICK	Full range	0	-	V ⁺ -2.0	_	—	V*-2.0	v	v =30[v]	00
Supply Current	ICC	25°C	I	0.4	1	_	0.8	2.0	mA	RL=∞,V ⁺ =5[V]	- 89
Supply Current	100	23 0	-	1	2.5	_	1.0	2.5	IIIA	RL=∞,V ⁺ =36[V]	
Large Signal Voltage Gain	AVD	25°C	25	200	_	25	100	-	V/mV	V ⁺ =15[V],VO=1[V] to 11[V] RL≧15[kΩ]	88
Large Signal Response Time	tREL	25°C	_	300	_	_	300	_	ns	VIN=TTL logic swing, Vref=1.4[V] VRL=5[V],RL=5.1[kΩ]	89
Response Time	tRE	25°C	1.5			_	1.3	_	μs	VRL=5[V],RL=5.1[kΩ] VIN=100[mVp-p] overdrive=5[mV]	89
Output Sink Current	ISINK	25°C	6	16	_	6	16	-	mA	VIN(-)=1[V],VIN(+)=0[V] VO≦1.5[V]	89
		25°C	_	250	400	_	250	400	.,	VIN(-)=1[V],VIN(+)=0[V]	
Output Saturation Voltage	VOL	Full range	I	_	700	_	_	700	mV	ISINK≦4[mA]	89
		25°C		0.1		_	0.1	-	nA	VIN(-)=0[V],VIN(+)=1[V],	90
Output Leakage Current	IOH	Full range	_	0.1	-	_	-	1.0	μA	VO=5[V]	89
Differential Input Voltage	VID	Full range	_	_	36	_	_	36	V	ALL VIN≧0[V]	_

(*1) Absolute value

					Lir	nit						
Parameter	Symbol	Temperature range	LM2903 family			LM2901 family			Unit	Condition	Fig.N o.	
		Ū	Min.	Тур.	Max.	Min.	Тур.	Max.				
Input Offset Voltage (*2)	VIO	25°C	_	2	7	_	2	7	mV	V ⁺ =30[V],VO=1.4[V], RS=0[Ω]	88	
input Onset voltage (2)	VIO	Full range	-	9	15	-	9	15	mv	VCM=0[V] to V ⁺ -1.5[V]	00	
Input Bias Current (*2)	IIB	25°C	_	25	250	_	25	250	nA	IIN(+) or IIN(-)	88	
Input bias Current (2)	IID	Full range	_	200	500	_	200	500	na	VCM=0[V]	00	
Input Offect Current (*2)	IIO	25°C	—	5	50	—	5	50	54		88	
Input Offset Current (*2)	IIO	Full range	_	50	200	_	50	200	nA	IIN(+)-IIN(-),VCM=0[V]	00	
Input Common-mode	VICR	25°C	—	-	V ⁺ -1.5	—	-	V ⁺ -1.5	v	V ⁺ =30[V]	00	
Voltage Range	VICK	Full range	-	-	V*-2.0	_	-	V ⁺ -2.0	v	v =30[v]	88	
Supply Current	100	or°o	_	0.4	1	_	0.8	2		RL=∞,V*=5[V]	- 89	
Supply Current	oly Current ICC 25°C -	1	2.5	_	1	2.5	mA	RL=∞,V ⁺ =36[V]				
Voltage Gain	AVD	25℃	25	100	_	25	100	_	V/mV	V^+ =15[V],VO=1[V] to 11[V], RL≧15[kΩ]	88	
Large Signal Response Time	tREL	25°C	_	300	_	_	300	_	ns	VIN=TTL logic swing, Vref=1.4[V] VRL=5[V],RL=5.1[kΩ]	89	
Response Time	tRE	25°C	_	1.5	_	_	1.3	_	μs	VRL=5[V],RL=5.1[kΩ] VIN=100[mVp-p], overdrive=5[mV]	89	
Output Sink Current	ISINK	25°C	6	16	_	6	16	_	mA	VIN(-)=1[V],VIN(+)=0[V] VO≦1.5[V]	89	
		25°C	_	250	400	-	250	400		VIN(-)=1[V],VIN(+)=0[V]		
Saturation Voltage	VOL	Full range	_	400	700	_	_	700	mV	ISINK≦4[mA]	89	
		25°C	_	0.1	_	_	0.1	_	nA	VIN(-)=0[V],VIN(+)=1[V], VO=5[V]		
Output Leakage Current	lleak	Full range	_	_	1	_	_	1	μA	VIN(-)=0[V],VIN(+)=1[V], VO=30[V]	- 89	
Differential Input Voltage	VID	Full range	_	_	36	_	_	36	v	ALL VIN≧0[V]	-	

OLM2903/2901 family(Unless otherwise specified, V+=+5[V])

(*2) Absolute value

Reference Data LM393 family





80

40



(*)The data above is ability value of sample, it is not guaranteed. LM393family: 0[°C]~+70[°C]

5

6V

+

۱ 2۷

AMBIENT TEMPERATURE [°C]

20 30 40 50 60 70 AMBIENT TEMPERATURE [°C]

Fig. 18

- Ambient Temperature

Fig. 15

- Ambient Temperature

20 30 40 50 60

10

10

LM 393 family

70 80

M 393 fami

80

Reference Data LM393 family



(*)The data above is ability value of sample, it is not guaranteed. LM393family:0[°C]~+70[°C]

Reference Data LM339 family

LM 339 family LM 339 family 1000 1 0°C 0.8 800 0.8 POWER DISSIPATION [mW] SUPPLY CURRENT [mA] иззэмх SUPPLY CURRENT [md] 6\ 25°C 0.6 600 0.6 0.4 400 0.4 1 70°C 0.2 200 0.2 0 0 0 10 20 30 40 50 60 70 AMBIENT TEMPER ATURE [°C] 0 25 50 75 100 125 0 80 20 10 30 40 0 TEMPERATURE [°C] Fig.21 Y VOLTAGE [V] Fig.22 AMBIENT SUPPL Fig. 23 Derating Curve Supply Current - Supply Voltage Supply Current – Ambient Temperature LM 339 family LM 339 family 2.0 500 500 1.8 OUTPUT SATURATION VOLTAGE [mV] OUTPUT SATURATION VOLTAGE [mV] LOW LEVEL OUTPUT VOLTAGE [V] 70°C 1.6 400 400 2\ 1.4 25°C 12 300 300 70°C 10 Ś١ 200 200 0.8 0.6 0°C 100 0.4 100 0°C 0.2 0 0.0 0 20 30 40 50 60 7 AMBIENT TEMPERATURE [°C] 0 10 20 30 SUPPLY VOLTAGE [V] 40 80 0 2 4 6 8 10 12 14 16 18 20 10 70 30 0 OUTPUT SINK CURRENT [mA] Fig.24 Fig. 25 Fig. 26 Output Saturation Voltage **Output Saturation Voltage** Low Level Output Voltage Output Sink Current Supply Voltage - Ambient Temperature (IOL=4[mA])(IOL=4[mÅ]) . (VCC=5[V]) LM 339 family LM 339 family LM 339 family 8 8 40 6 6 INPUT OFFSET VOLTAGE [mV] INPUT OFFSET VOLTAGE [mV] OUTPUT SINK CURR ENT [mA] 4 4 30 0°C 2 2 36\/ 25°C 0 0 20 -2 -2 70°C 36 -4 10 -4 -6 -6 -8 -8 0 20 30 40 50 60 70 80 0 10 20 30 40 0 10 20 30 40 50 60 70 80 10 0 AMBIENTTEMPERATURE [°C] SUPPLY VOLTAGE [V] AMBIENT TEMPERATURE [°C] Fig. 28 Fig. 27 Fig. 29 Output Sink Current – Ambient Temperature (VOUT=1.5[V]) Input Offset Voltage - Supply Voltage Input Offset Voltage - Ambient Temperature LM 339 family LM 339 famil LM 339 famil 160 50 160 40 140 140 INPUT OFFSET CURRENT [nA] 30 INPUT BIAS CURRENT [nA] 120 INPUT BIAS CURRENT [nA] 120 20 100 100 10 80 0 80 25°C -10 60 60 -20 40 40 -30 70°0 2V 20 20 -40 0 0 -50 0 20 30 SUPPLY VOLTAGE [V] 0 10 20 30 40 50 60 70 80 40 0 10 40 0 10 20 30 AMBIENT TEMPERATURE [°C] SUPPLY VOLTAGE [V] Fig. 30 Fig. 31 Fig. 32 Input Bias Current - Supply Voltage Input Offset Current - Supply Voltage Input Bias Current – Ambient Temperature

(*)The data above is ability value of sample, it is not guaranteed. LM339family:0[°C]~+70[°C]

51

36V

۱ 2۷

30 40 50 60

Fig. 35

Fig. 38

LM 339 family

70 80

LM 339 family

80

Reference Data LM339 family LM 339 family LM 339 family 50 140 140 40 130 130 LARGE SIGNAL VOLTAGE GAIN [dB] LARGE SIGNAL VOLTAGE GAIN [dB] NPUT OFFSET CURRENT [hA] 36\ 30 120 120 20 110 110 10 0 100 100 0°C -10 90 90 2V -20 80 80 -30 70 -40 70 -50 60 60 20 30 40 50 0 10 60 70 80 10 20 30 SUPPLY VOLTAGE [V] 0 20 0 40 10 AMBIENT TEMPERATURE [°C] AMBIENT TEMPERATURE [°C] Fig. 34 Fig. 33 Input Offset Current Large Signal Voltage Gain Large Signal Voltage Gain - Supply Voltage - Ambient Temperature - Ambient Temperature LM 339 family LM 339 family 160 140 140 POWER SUPPLY REJECTION RATIO [dB] COMMON MODE REJECTION RATIO[dB] POWER SUPPLY REJECTION RATIO [dB] 130 130 140 120 120 36V 120 0°C 110 110 25°C ·100 100 100 90 90 80 80 80 2V 60 70 70 40 60 60 40 50 60 20 40 10 20 30 70 20 30 40 50 60 70 AMBIENT TEMPERATURE [°C] 0 10 30 0 80 0 10 SUPPLY VOLTAGE [V] AMBIENT TEMPERATURE [°C] Fig. 36 Fig. 37 Common Mode Rejection Ratio Common Mode Rejection Ratio Power Supply Rejection Ratio - Supply Voltage - Ambient Temperature - Ambient Temperature LM 339 family LM 339 family 5 5 RESPONSE TIME (HIGH to LOW) [µs] RESPONSE TIME (LOW to HIGH) [µs] 4 4 3 3 erd ۶m۷ 2 2 100 20m ove 1 1 100r ove 0 0 0 20 30 40 50 60 7 AMBIENT TEMPERATURE [°C] 40 50 60 70 0 10 70 80 10 20 30 80 0 AMBIENT TEMPERATURE [°C] Fig. 39 Fig. 40 Response Time (Low to High) Response Time (High to Low) - Ambient Temperature -Ambient Temperature (VCC=5[V],VRL=5[V],RL=5.1[kΩ]) (VCC=5[V],VRL=5[V],RL=5.1[kΩ])

(*)The data above is ability value of sample, it is not guaranteed. LM339family:0[°C]~+70[°C]



(*)The data above is ability value of sample, it is not guaranteed.LM2903family:-40[°C]~+85[°C]



(*)The data above is ability value of sample, it is not guaranteed. LM2903family:-40[°C] \sim +85[°C]



(*)The data above is ability value of sample, it is not guaranteed.LM2903family:-40[°C] \sim +85[°C]

Reference Data LM2901 family LM 2901 family LM 2901 family LM 2901 family 50 140 140 LARGE SINGAL VOLTAGE GAIN [dB] LARGE SINGAL VOLTAGE GAIN [dB] 40 130 130 5°C INPUT OFFSET CURRENT [nA] 30 361/ 120 120 20 2V 110 110 10 0 100 100 25°C 5\ 15\ -40°C -10 5V 90 90 36\ -20 80 80 -30 70 70 -40 -50 60 60 75 100 125 150 -50 -25 0 25 50 0 -50 -25 0 25 50 75 100 125 150 10 20 30 40 AMBIENT TEMPERATURE [°C] SUPPLY VOLTAGE [V] AMBIENT TEMPERATURE [°C] Fig. 76 Fig. 78 Fig. 77 Input Offset Current – Ambient Temperature Large Signal Voltage Gain Large Signal Voltage Gain Supply Voltage - Ambient Temperature LM 2901 family LM 2901 family LM 2901 family 150 6 160 [dB] COMMON MODE REJECTION RATIO [dB] COMMON MODE REJECTION RATIO 25°C 85°C INPUT OFFSET VOLTAGE [mV] 125 140 4 36V -40°C 120 100 2 85°C 100 75 0 5) 80 50 -2 25° -40°C 60 25 -4 0 40 -6 0 10 20 30 40 -50 -25 0 25 50 75 100 125 150 0 2 3 5 -1 4 AMBIENT TEMPERATURE [°C] SUPPLY VOLTAGE [V] INPUT VOLTAGE [V] Fig. 79 Fig. 80 Fig. 81 Common Mode Rejection Ratio Common Mode Rejection Ratio Input Offset Voltage - Input Voltage (VCC=5V) - Supply Voltage Ambient Temperature LM 2901 family LM 2901 family LM 2901 family 200 5 5 POWER SUPPLY REJECTION RATIO [dB] RRESPONSE TIME (LOW TO HIGH)[µs] RESPONSE TIME (LOW TO HIGH)[µs] 180 4 4 160 3 3 140 100mV 5m∖ drive overdrive 120 2 20m\ 2 85°C 100 -40 25°C 1 1 80 0 60 0 -50 0 25 50 75 100 125 150 -50 -25 0 25 50 75 100 125 150 -100 -80 -60 -40 -20 0 -25 AMBIENT TEMPERATURE [°C] AMBIENT TEMPERATURE [°C] OVER DRIVE VOLTAGE [V] Fig. 82 Fig. 83 Fig. 84 Response Time (Low to High) Response Time (Low to High) Power Supply Rejection Ratio Ambient Temperature (VCC=5[V],VRL=5[V],RL=5.1[kΩ]) - Over Drive Voltage - Ambient Temperature (VCC=5[V],VRL=5[V],RL=5.1[kΩ]) LM 2901 family LM 2901 family 5 5 RESPONSE TIME (HIGH TO LOW)[µs] RESPONSE TIME (HIGH TO LOW)[µs] 4 4 100mV overdrive 3 3 20mV overdrive 85°C 2 2 25°C -40°C 1 1 0 0 50 75 -50 -25 0 25 100 125 150 0 20 100 40 60 80 AMBIENT TEMPERATURE [°C] OVER DRIVE VOLTAGE [V] Fig. 85 Fig. 86 Response Time (High to Low) Response Time (High to Low) - Ambient Temperature Over Drive Voltage

(*)The data above is ability value of sample, it is not guaranteed. LM2903family:-40[°C]~+85[°C]

●Circuit Diagram



Fig.87 Circuit Diagram (each Comparator)

Me	easurement	circuit 1 N	UL	L Meth	od mea	surem	ent con	dition	

easurement circuit 1 NUL	L Meth	od mea	asurem	ent con	dition				V*	,GND,EK	,VICR ur	nit : [V]	
Deremeter	VF	S1	S2	S3	L	LM393/LM339 family				LM2903/LM2901 family			
Parameter	VF	51	52	53	V *	GND	EK	VICR	V *	GND	EK	VICR	Calculation
Input Offset Voltage	VF1	ON	ON	ON	5 to 30	0	-1.4	0	5 to 30	0	-1.4	0	1
Input Offset Current	VF2	OFF	OFF	ON	5	0	-1.4	0	5	0	-1.4	0	2
Input Bias Current	VF3	OFF	ON	ON	5	0	-1.4	0	5	0	-1.4	0	3
Input Bias Current	VF4	ON	OFF	ON	5	0	-1.4	0	5	0	-1.4	0	3
	VF5	ON			15	0	-1.4	0	15	0	-1.4	0	4
Voltage Gain	VF6	ON	ON	ON ON	15	0	-11.4	0	15	0	-11.4	0	4

-Calculation-

1.Input offset voltage (VIO)

$$Vio = \frac{|VF1|}{1+Rf/Rs} [V]$$

2.Input offset current (IIO)

$$lio = \frac{|VF2 - VF1|}{Ri(1 + Rf / Rs)} [A]$$

3.Input bias current (IIb)

$$Ib = \frac{|VF4 - VF3|}{2x Ri(1 + Rf / Rs)} [A]$$

4.Voltage gain (AVD)

$$AV = 20x Log \frac{10x (1 + Rf/Rs)}{|VF6 - VF5|} [dB]$$



Fig.88 Measurement Circuit1 (each Comparator)

SW No		SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7
Supply Current	_	OFF						
Output Sink Current	VOL=1.5[V]	OFF	ON	ON	OFF	ON	ON	OFF
Saturation Voltage	IOL=4[mA]	OFF	ON	ON	OFF	OFF	OFF	ON
Output Leakage Current	VOH=36[V]	OFF	ON	ON	OFF	OFF	OFF	ON
Deepense Time	RL=5.1[kΩ]	ON	OFF	ON	ON	OFF	ON	OFF
Response Time	VRL=5[V]		OFF			UFF	UN	OFF

Measurement Circuit 2: Switch Condition



Fig.89 Measurement Circuit 2 (each Comparator)



Description of electrical characteristics

Described below are descriptions of the relevant electrical terms. Please note that item names, symbols, and their meanings may differ from those on another manufacturer's documents.

1. Absolute maximum ratings

The absolute maximum ratings are values that should never be exceeded, since doing so may result in deterioration of electrical characteristics or damage to the part itself as well as peripheral components.

- 1.1 Power supply voltage (V⁺/GND) Expresses the maximum voltage that can be supplied between the positive and negative power supply terminals without causing deterioration of the electrical characteristics or destruction of the internal circuitry.
- 1.2 Differential input voltage (VID)

Indicates the maximum voltage that can be supplied between the non-inverting and inverting terminals without damaging the IC.

1.3 Input common-mode voltage range (VICR)

Signifies the maximum voltage that can be supplied to non-inverting and inverting terminals without causing deterioration of the electrical characteristics or damage to the IC itself. Normal operation is not guaranteed within the input common-mode voltage range of the maximum ratings – use within the input common-mode voltage range of the electric characteristics instead.

- 1.4 Operating temperature range and storage temperature range (Topr,Tstg) The operating temperature range indicates the temperature range within which the IC can operate. The higher the ambient temperature, the lower the power consumption of the IC. The storage temperature range denotes the range of temperatures the IC can be stored under without causing excessive deterioration of the electrical characteristics.
- 1.5 Power dissipation (Pd)

Indicates the power that can be consumed by a particular mounted board at ambient temperature (25°C). For packaged products, Pd is determined by maximum junction temperature and the thermal resistance.

- 2. Electrical characteristics
- 2.1 Input offset voltage (VIO)

Signifies the voltage difference between the non-inverting and inverting terminals. It can be thought of as the input voltage difference required for setting the output voltage to 0V.

- 2.2 Input offset current (IIO) Indicates the difference of the input bias current between the non-inverting and inverting terminals.
- 2.3 Input bias current (IIB)

Denotes the current that flows into or out of the input terminal, it is defined by the average of the input bias current at the non-inverting terminal and the input bias current at the inverting terminal.

- 2.4 Input common-mode voltage range (VICR)
- Indicates the input voltage range under which the IC operates normally.
- 2.5 Large signal voltage gain (AVD)

The amplifying rate (gain) of the output voltage against the voltage difference between the non-inverting and inverting terminals, it is (normally) the amplifying rate (gain) with respect to DC voltage. AVD = (output voltage fluctuation) / (input offset fluctuation)

2.6 Circuit current (ICC)

Indicates the current of the IC itself that flows under specific conditions and during no-load steady state.

2.7 Output sink current (IOL)

Denotes the maximum current that can be output under specific output conditions.

- 2.8 Output saturation voltage low level output voltage (VOL) Signifies the voltage range that can be output under specific output conditions.
- 2.9 Output leakage current (ILeak)

Indicates the current that flows into the IC under specific input and output conditions.

- 2.10 Response time (tre) The interval between the application of input and output conditions.
- 2.11 Common-mode rejection ratio (CMRR) Denotes the ratio of fluctuation of the input offset voltage when the in-phase input voltage is changed (DC fluctuation). CMRR = (change of input common-mode voltage) / (input offset fluctuation)
- 2.12 Power supply rejection ratio (PSRR) Signifies the ratio of fluctuation of the input offset voltage when the supply voltage is changed (DC fluctuation). PSRR = (change in power supply voltage) / (input offset fluctuation)

θ ja [°C/W]

4.9 θja = (Tj-Ta)/Pd[°C/W]

NOW SERIES LM2903/2901/393/339 family

Derating Curves





Pd[W]

610

Package

SO package14

Package	Pd[W]	<i>θ</i> ja [°C/W]				
SO package8 (*8)	450	3.6				
θja = (Tj-Ta)/Pd[°C/W						

Fig.102 Derating Curves

Notes for use

1) Unused circuits

When there are unused circuits it is recommended that they be connected as in Fig. 103, setting the non-inverting input terminal to a potential within the in-phase input voltage range (VICR).

2) Input terminal voltage

Applying GND + 36V to the input terminal is possible without causing deterioration of the electrical characteristics or destruction, irrespective of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common mode input voltage range of the electric characteristics.



3) Power supply (single / dual)

The op-amp operates when the specified voltage supplied is between V^+ and GND. Therefore, the single supply op-amp can be used as a dual supply op-amp as well.

4) Power dissipation Pd

Using the unit in excess of the rated power dissipation may cause deterioration in electrical characteristics due to a rise in chip temperature, including reduced current capability. Therefore, please take into consideration the power dissipation (Pd) under actual operating conditions and apply a sufficient margin in thermal design. Refer to the thermal derating curves for more information.

- 5) Short-circuit between pins and erroneous mounting Incorrect mounting may damage the IC. In addition, the presence of foreign particles between the outputs, the output and the power supply, or the output and GND may result in IC destruction.
- 6) Terminal short-circuits When the output and V⁺ terminals are shorted, excessive output current may flow, resulting in undue heat generation and, subsequently, destruction.
- Operation in a strong electromagnetic field Operation in a strong electromagnetic field may cause malfunctions.
- 8) Radiation

This IC is not designed to withstand radiation.

- IC handing Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations in the electrical characteristics due to piezoelectric (piezo) effects.
- 10) Board inspection

Connecting a capacitor to a pin with low impedance may stress the IC. Therefore, discharging the capacitor after every process is recommended. In addition, when attaching and detaching the jig during the inspection phase, ensure that the power is turned OFF before inspection and removal. Furthermore, please take measures against ESD in the assembly process as well as during transportation and storage.

Ordering part number



S.O package8



S.O package14



Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment ^(Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA	
CLASSⅢ		CLASS II b		
CLASSⅣ	CLASSⅢ	CLASSⅢ	CLASSⅢ	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

Precaution Regarding Intellectual Property Rights

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data. ROHM shall not be in any way responsible or liable for infringement of any intellectual property rights or other damages arising from use of such information or data.:
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General Precaution

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
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